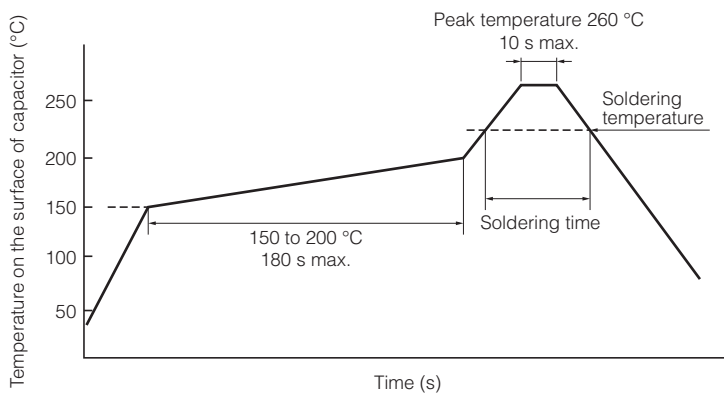


Mounting Specifications

- Recommendable reflow soldering

<Standard>



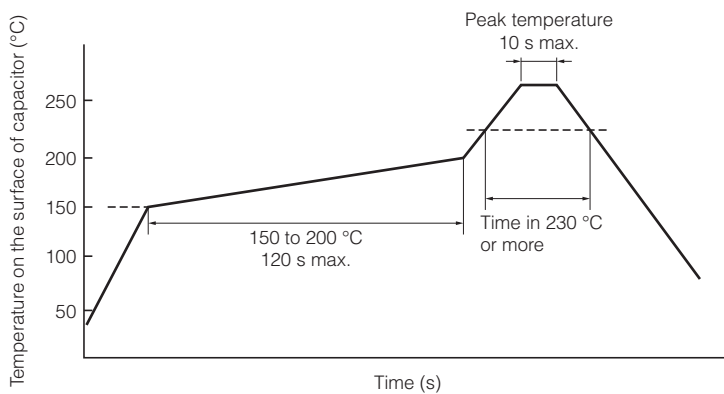
Reflow cycle : 3 max.

Soldering temperature and Soldering time

| Temperature | Time |
|-------------|------------|
| ≥ 255 °C | 30 s max. |
| ≥ 230 °C | 130 s max. |
| ≥ 217 °C | 150 s max. |

Sp-Cap recommended profile condition of the IPC/J-STD-020D standard

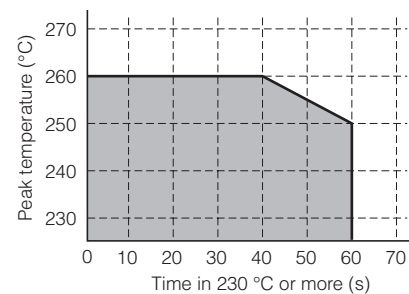
<260 °C>



Reflow cycle : 2 max.

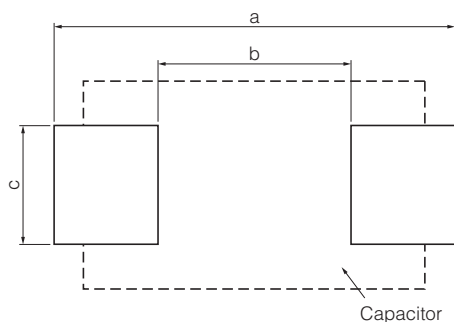
EX.)

| Peak temperature | Time in 230 °C or more |
|-------------------|------------------------|
| 260 °C, 10 s max. | 40 s max. |
| 250 °C, 10 s max. | 60 s max. |



- Typical land pattern

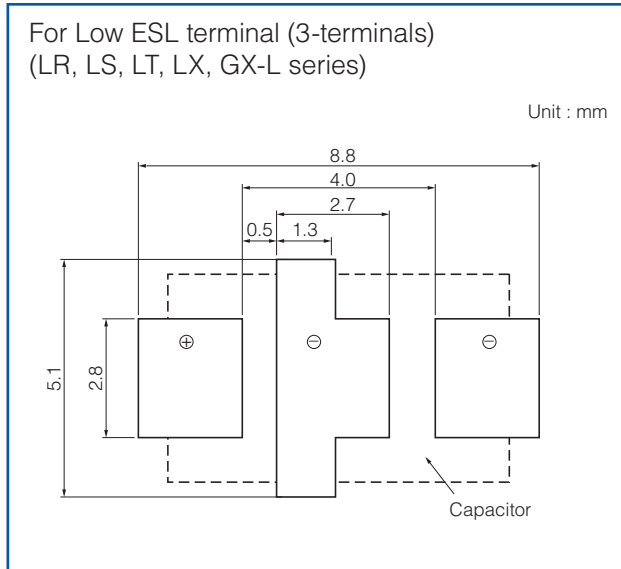
For standard terminal (2-terminals)



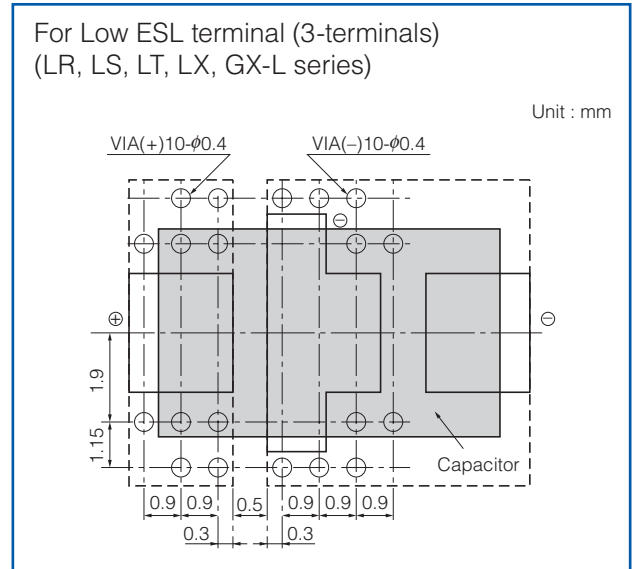
Unit : mm

| Series | a | b | c |
|----------------------|-----|-----|-----|
| Standard (Except MC) | 8.8 | 4.0 | 2.8 |
| (MC) | 7.2 | 2.6 | 2.2 |

● Typical land pattern

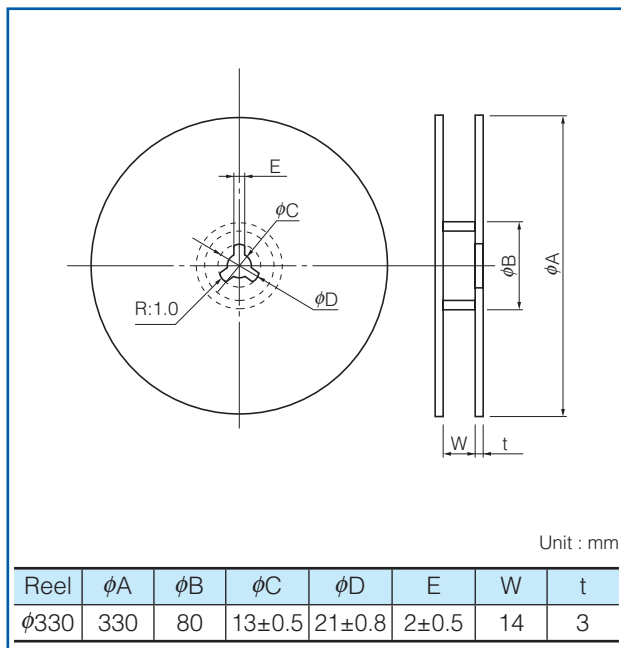


● VIA

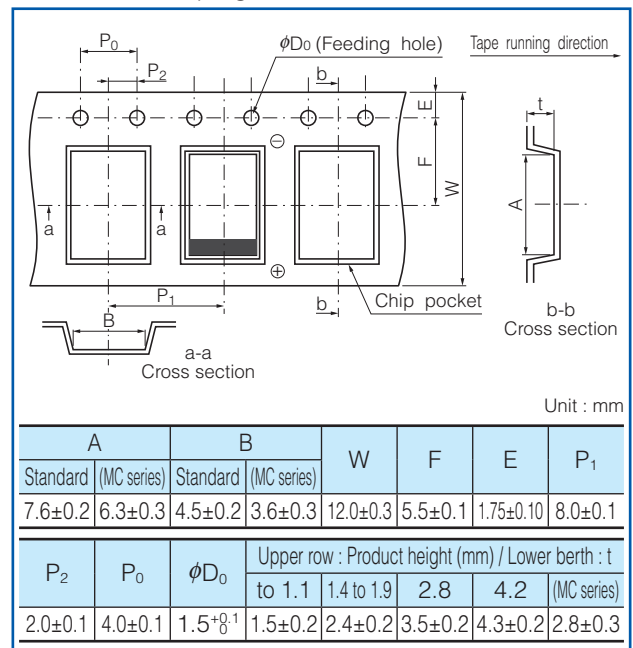


Packaging Specifications

● Reel Dimensions



● Embossed Taping



Packaging Box Dimensions

